MP6420

Battery Protection IC for 2-/3-Series Cell Li-Ion with Integrated Protective MOSFET and PTC Interface in TSOT23-8 Package

DESCRIPTION

The MP6420 provides over-charge protection that integrates a protective, open-drain MOSFET for 2- or 3-series cell Li-ion power systems.

The MP6420 provides a ±25mV, high-accuracy, over-charge threshold to monitor all series' battery pack conditions. With the high-accuracy threshold, the MP6420 can provide different fixed thresholds from 4.2V to 4.8V internally. Any cell over-charge that occurs turns on the internal protective MOSFET to indicate an error after an internally set, fixed delay time.

The MP6420 is available in a small, space-saving TSOT23-8 package.

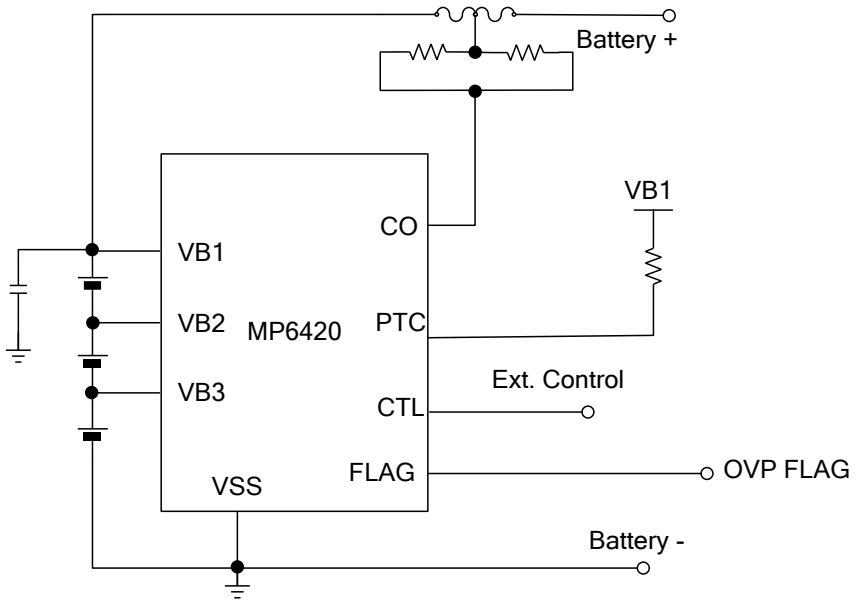
FEATURES

- Wide VB1 Range from 3.6V to 18V
- Fixed Over-Charge Threshold from 4.2V to 4.8V
- High-Accuracy ±25mV Over-Charge Threshold
- Supports 2- and 3-Series Cells
- Fixed Delay Time from 2s to 8s
- Integrated 24V/100mΩ Protective MOSFETs
- Low Quiescent Current: 3µA
- Over-Voltage Protection (OVP) Indicator (FLAG) and PTC Interface
- External Control (CTL)
- Available in a TSOT23-8 Package

APPLICATIONS

- Battery Packs
- Uninterruptible Power Supply (UPS)
- Power Tools

TYPICAL APPLICATION



ORDERING INFORMATION

Part Number*	Package	Top Marking
MP6420GJ	TSOT23-8	*See Below*

* For Tape & Reel, add suffix –Z (e.g. MP6420GJ–Z)

TOP MARKING

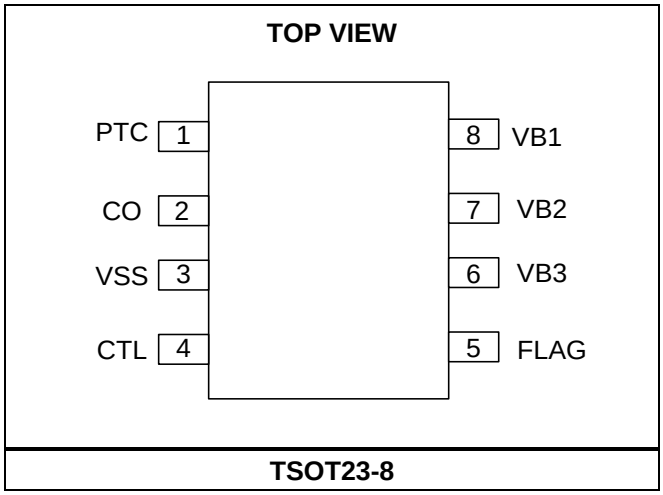
|AVFY

AVF: Product code of MP6420GJ
Y: Year code

OVER-VOLTAGE THRESHOLD

Part Number	Over-Voltage Threshold (V_{OV})	Over-Voltage Threshold (V_{OV_H})	Over-Voltage Delay Time
MP6420GJ-445	4.45V ± 25mV	-0.4 ± 0.16V	3.8 ± 0.8s

PACKAGE REFERENCE



TSOT23-8

ABSOLUTE MAXIMUM RATINGS (1)

VB1, PTC, CO ..... V_{SS} - 0.3V to V_{SS} + 19.5V
CTL, FLAG ..... V_{SS} - 0.3V to 6V
VB1 to VB2, VB2 to VB3 ..... V_{SS} - 0.3V to 6.5V
VB3 to VSS ..... V_{SS} - 0.3V to 6.5V
All other pins ..... V_{SS} - 0.3V to 6V
Junction temperature ..... 150°C
Lead temperature ..... 260°C
Continuous power dissipation (2)
TSOT23-8 (4) 1.2W

Recommended Operating Conditions (3)

Supply voltage (VB1) ..... 3.6V to 18V
Operating junction temp. (T_J) ... -40°C to +125°C

Thermal Resistance (4)	θ_{JA}	θ_{JC}	
TSOT23-8			
JESD51-7 (4)	100	55	°C/W
EV6420-J-00A (5)	100	26	°C/W

NOTES:

1) Exceeding these ratings may damage the device.
2) The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-to-ambient thermal resistance θ_{JA}, and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX)-T_A)/θ_{JA}. Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
3) The device is not guaranteed to function outside of its operating conditions.
4) Measured on JESD51-7, 4-layer PCB.
5) Measured on EV6420-J-00A,2-player PCB.

ELECTRICAL CHARACTERISTICS

V_{B1} = 12V, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V, T_J = -40°C to +125°C, typical value is tested at T_J = 25°C. The limit over temperature is guaranteed by characterization, unless otherwise noted.

Parameters	Symbol	Condition	Min	Typ	Max	Units
Input and Supply Voltage Range						
Input voltage	V_{B1}	V_{B1} voltage	3.6		18	V
V_{B1} under-voltage lockout threshold	V_{B1_UVLO}	Rising edge		3.2	4	V
UVLO hysteresis (8)	V_{B1_HYS}			200		mV
Quiescent current	I_Q	Normal condition (6) (7)		3	5	µA
Quiescent current during over-discharge		Over-discharge condition, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 3.3V		2		µA
Over-discharge cell voltage	V_{Dis}	Falling edge, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS}	3.5	3.8	4.1	V
Over-discharge cell voltage hysteresis				60		mV
Quiescent current during shutdown		Over-discharge condition, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 2.2V		1		µA
V_{BX} leakage current	I_{BX}	Normal condition (6) (7)		0		µA
Voltage Threshold						
Over-charge threshold	V_{OV}	See ordering info		V_{OV}		V
Over-charge threshold range		T_J = 25°C	-25		25	mV
		T_J = 85°C (8)	-30		45	
		T_J = -40°C (8)	-50		30	
Over-charge hysteresis	V_{OV_H}	See ordering info		V_{OV_H}		mV
Over-charge hysteresis range		T_J = 25°C	-160		160	mV
Protective MOSFET						
On resistance	$R_{DS(ON)}$	V_{B1} = 5.0V, single channel		100		mΩ
Current capability		Guaranteed by design	4.5			A
Breakdown voltage			28			V
Resistor between FLAG and CTL				240		kΩ
FLAG low voltage		Sink 1mA			0.5	V
FLAG high voltage		Source 1mA	4		5.5	V
CTL low voltage		V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 3.7V, sink 1µA			0.3	V
CTL high voltage		V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4.5V, source 1µA load	4	4.5	5.5	V
CTL rising threshold		Turn on the protective MOSFET		2		V
CTL falling threshold		Turn off the protective MOSFET		1.5		V
PTC Interface						
PTC threshold		Falling edge		V_{B1}-1.2		V
PTC hysteresis		Rising edge		400		mV
PTC deglitch delay		Guaranteed by design		100		µs

ELECTRICAL CHARACTERISTICS *(continued)*

V_{B1} = 12V, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V, T_J = -40°C to +125°C, typical value is tested at T_J = 25°C. The limit over temperature is guaranteed by characterization, unless otherwise noted.

Parameters	Symbol	Condition	Min	Typ	Max	Units
Delay Time						
Over-charge response delay	T_{OV}	Any V_{BX} over-charge	3	3.8	4.6	s
Over-charge reset time	T_{OV_RES}			10		ms
Over-charge release delay	T_{OV_N}			60		ms
PTC response delay		Before turning on protective MOSFET		1.8		ms
Over-discharge recovery delay		From over-discharge to normal mode		1		ms
Internal Filter						
Filter resistor (9)				3		MΩ
Filter capacitor (9)				100		pF

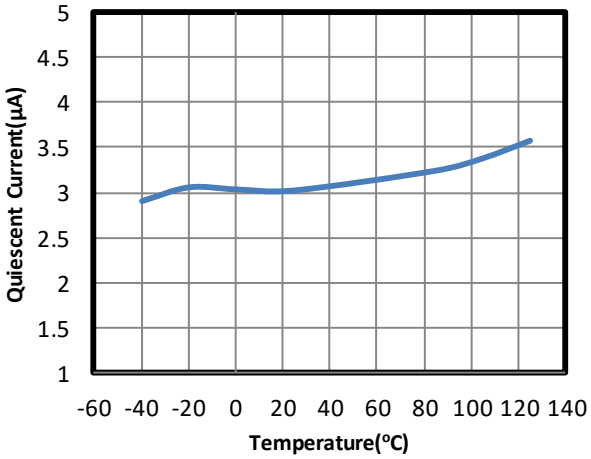
NOTES:

6) Normal condition means no over-charge condition occurred. V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V.
7) Test schematic excludes FLAG sink current.
8) Not tested in production, guaranteed by design specification.
9) Guaranteed by design.

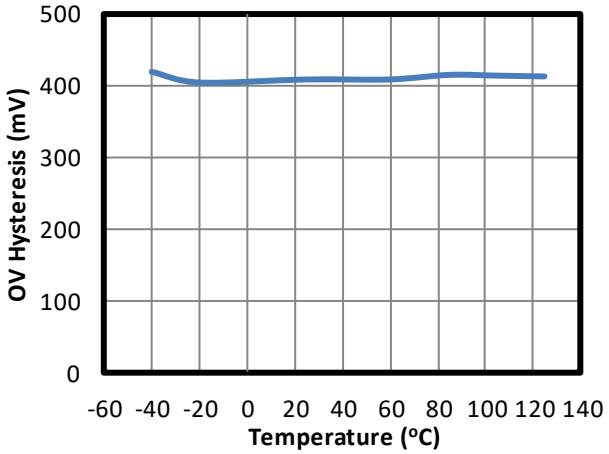
TYPICAL CHARACTERISTICS

V_{B1} = 12V, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V, T_J = -40°C to +125°C. Test based on MP6420GJ-445, unless otherwise noted.

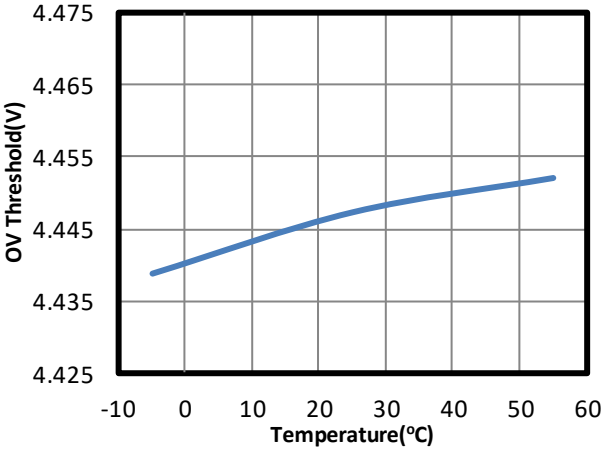
Quiescent Current vs. Temperature



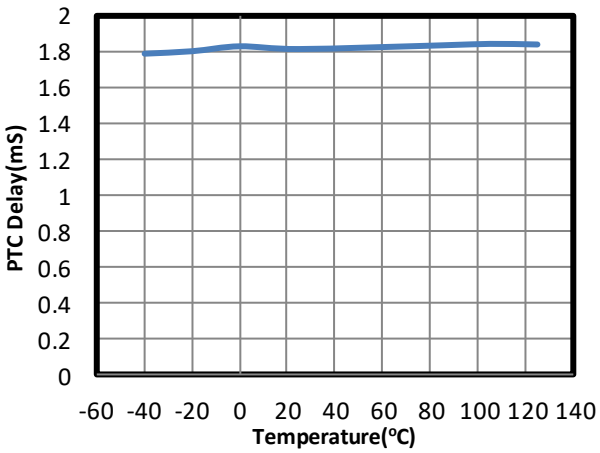
OV Hysteresis vs. Temperature



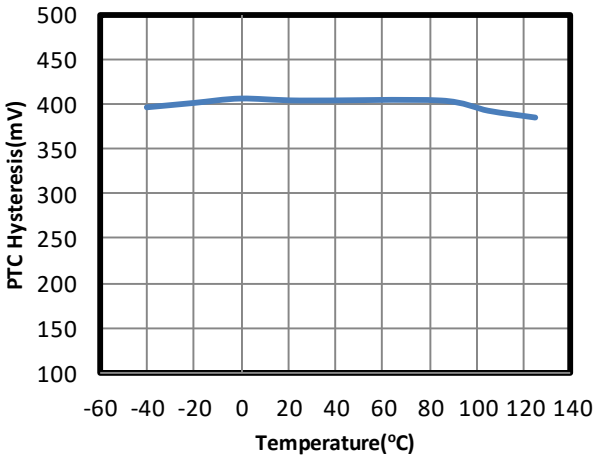
OV Threshold Vs. Temperature



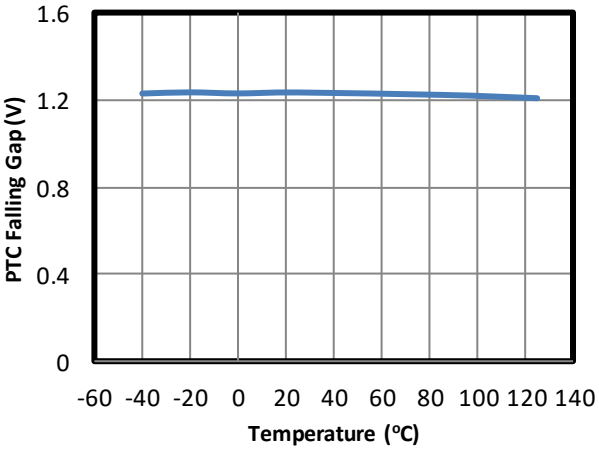
PTC Delay vs. Temperature



PTC Hysteresis vs. Temperature



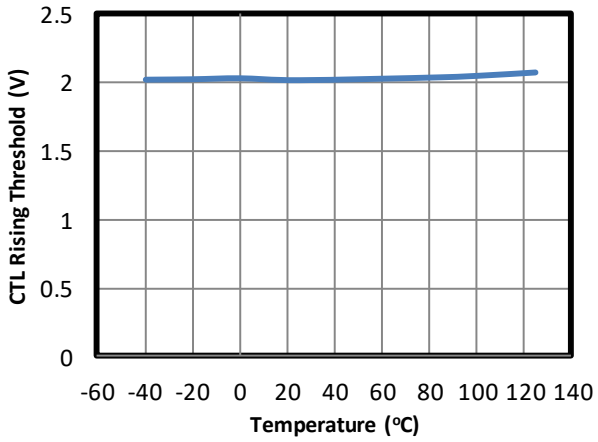
PTC Falling Gap vs. Temperature



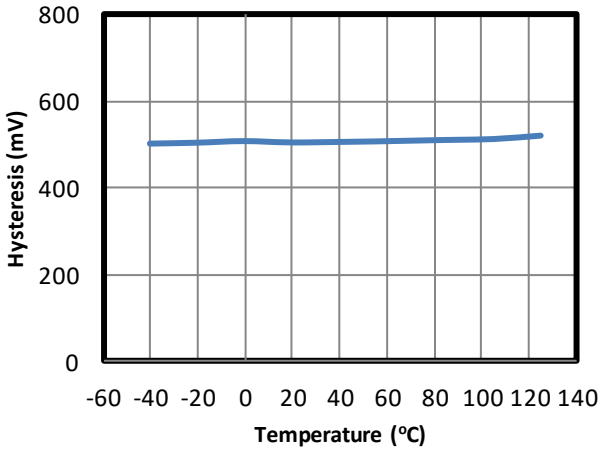
TYPICAL CHARACTERISTICS *(continued)*

V_{B1} = 12V, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V, T_J = -40°C to +125°C. Test based on MP6420GJ-445, unless otherwise noted.

CTL Rising Threshold vs. Temperature

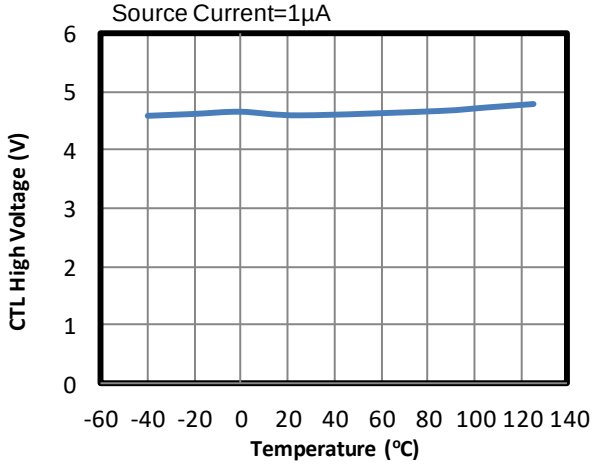


CTL Hysteresis vs. Temperature



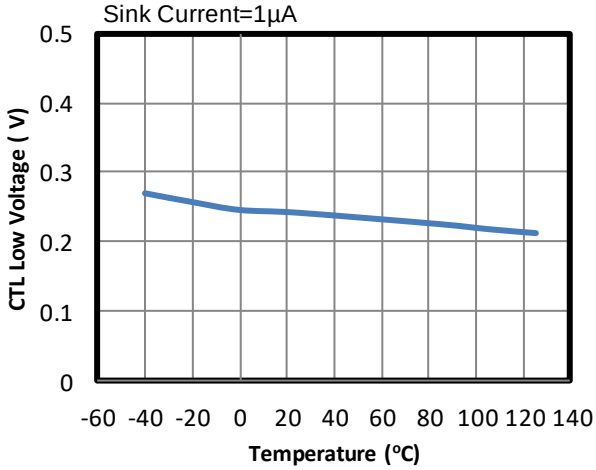
CTL High Voltage vs. Temperature

Source Current=1µA



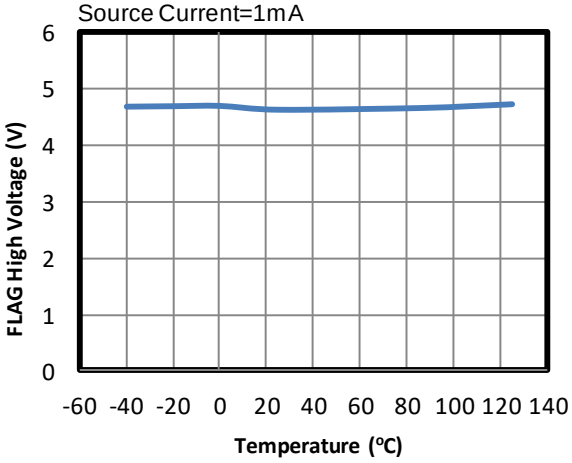
CTL Low voltage vs. Temperature

Sink Current=1µA



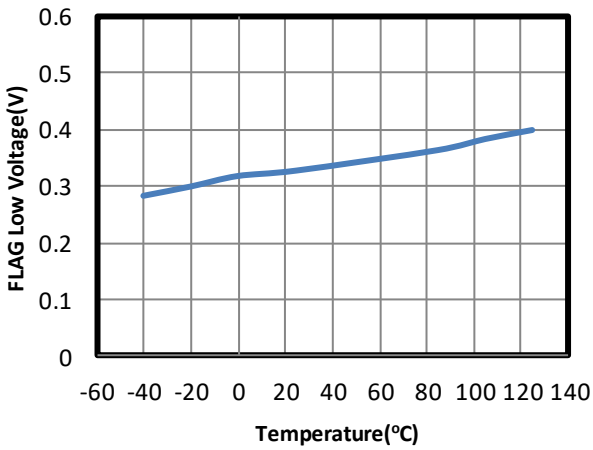
FLAG High Voltage vs. Temperature

Source Current=1mA



FLAG Low Voltage vs. Temperature

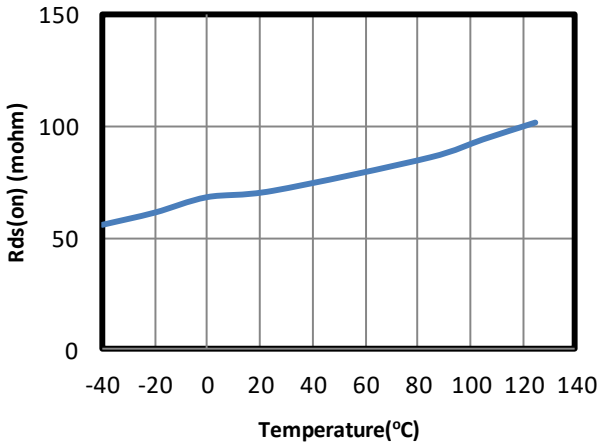
Sink Current=1mA



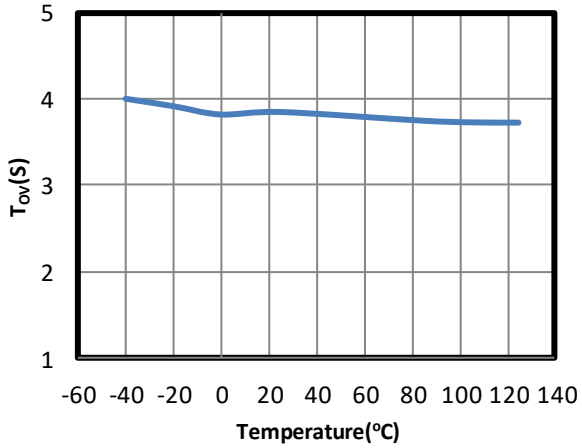
TYPICAL CHARACTERISTICS *(continued)*

V_{B1} = 12V, V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V, T_J = -40°C to +125°C. Test based on MP6420GJ-445, unless otherwise noted.

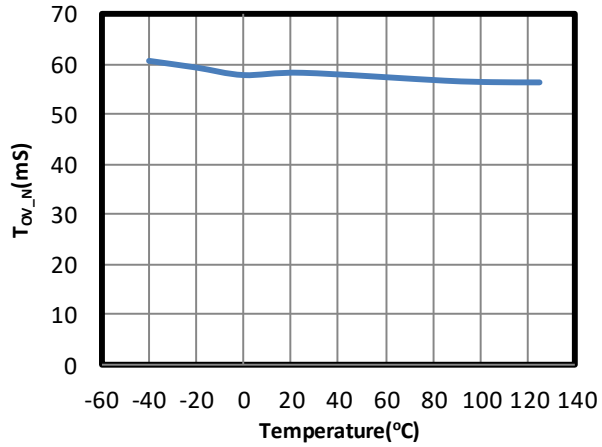
Rds(on) vs. Temperature



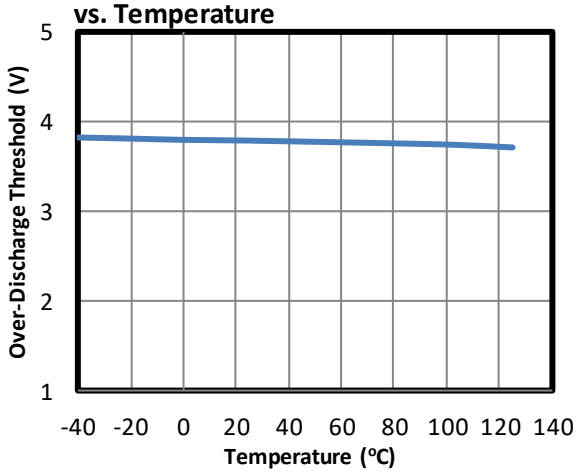
T_{OV} vs. Temperature



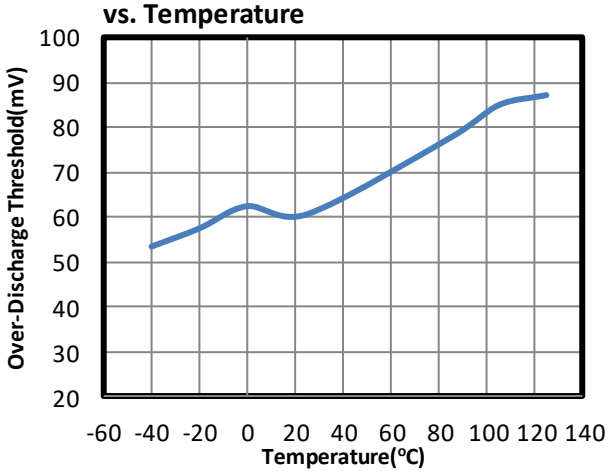
T_{OV_N} vs. Temperature



Over-Discharge Threshold vs. Temperature



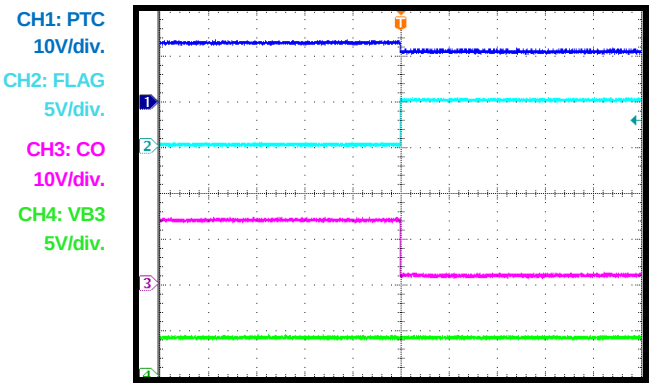
OV-Discharge Hysteresis vs. Temperature



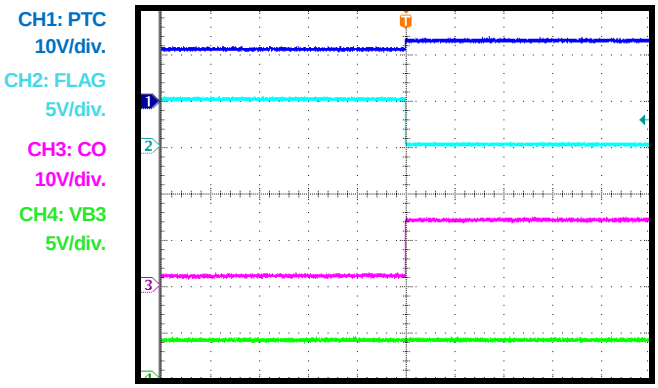
TYPICAL PERFORMANCE CHARACTERISTICS

V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V with 10kΩ resistor between VB1 and PTC, T_J = 25°C. Test based on MP6420GJ-445, unless otherwise noted.

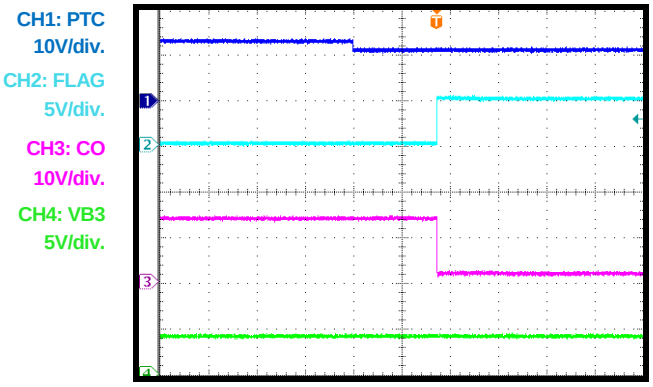
PTC Response



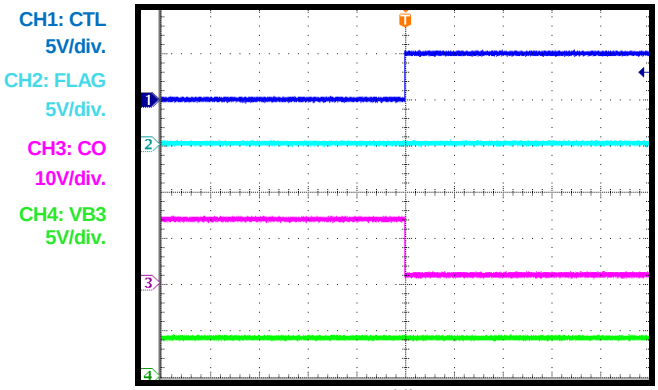
PTC Response



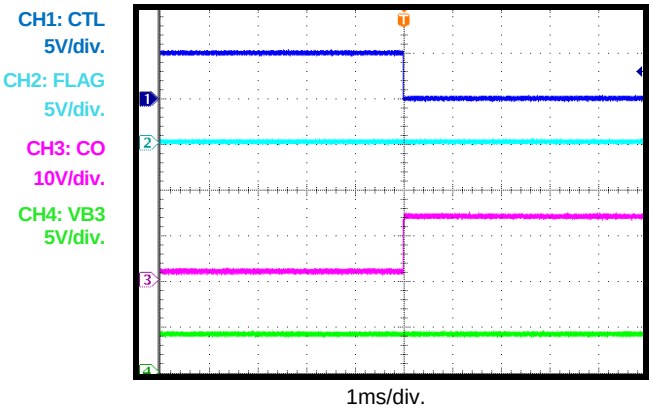
PTC Delay



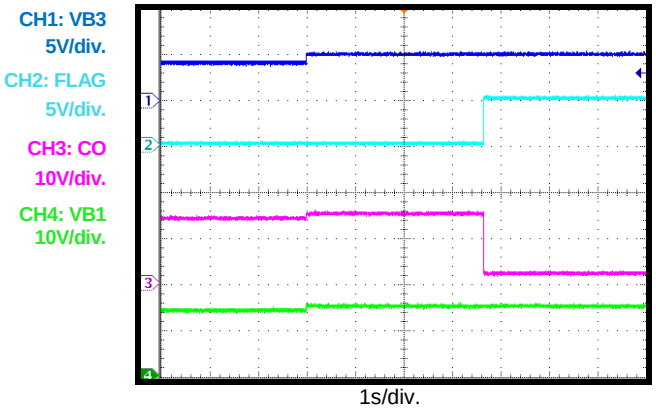
CTL Response



CTL Response



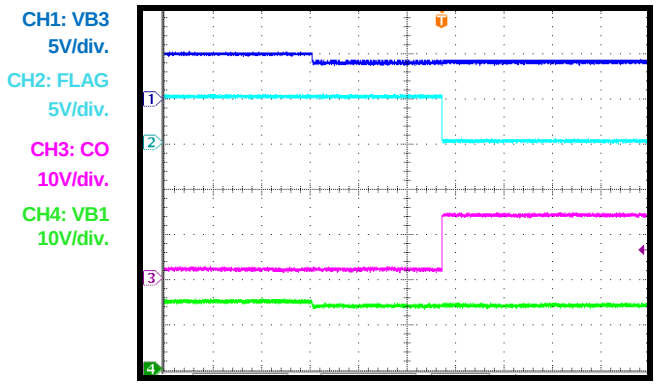
OVP Response



TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{B1} to V_{B2} = V_{B2} to V_{B3} = V_{B3} to V_{SS} = 4V with 10kΩ resistor between VB1 and PTC, T_J = 25°C. Test based on MP6420GJ-445, unless otherwise noted.

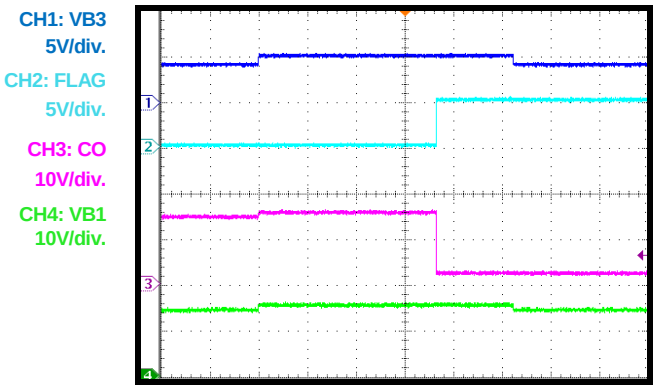
OVP Recovery Delay



20ms/div.

OVP Response

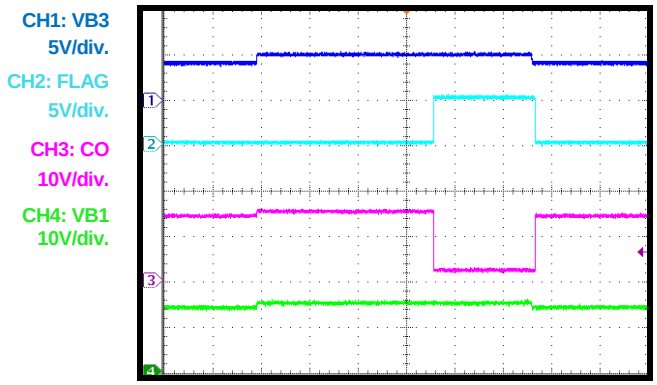
VB1 to VB2 = VB2 to VB3 = 4.1V



1s/div.

OVP Recovery

VB1 to VB2 = VB2 to VB3 = 3.9V



1s/div.

PIN FUNCTIONS

Package Pin #	Name	Description
1	PTC	**Positive thermal coefficient interface.**
2	CO	**Open-drain output of the protective MOSFET.**
3	VSS	**Negative power supply.**
4	CTL	**External control.** CTL connects to the gate pin of the internal protective MOSFET.
5	FLAG	**Battery OVP indicator.** When OVP occurs and the internal protective MOSFET turns on, FLAG is pulled up to at least 4V.
6	VB3	**Voltage sense point of battery cell 3.** VB3 is connected to the positive voltage of cell 3. Place cell 2 between VB2 and VB3.
7	VB2	**Voltage sense point of battery cell 2.** VB2 is connected to the positive voltage of cell 2. Place cell 1 between VB1 and VB2.
8	VB1	**Voltage sense point of battery cell 1.** VB1 is connected to the positive voltage of cell 1.

BLOCK DIAGRAM

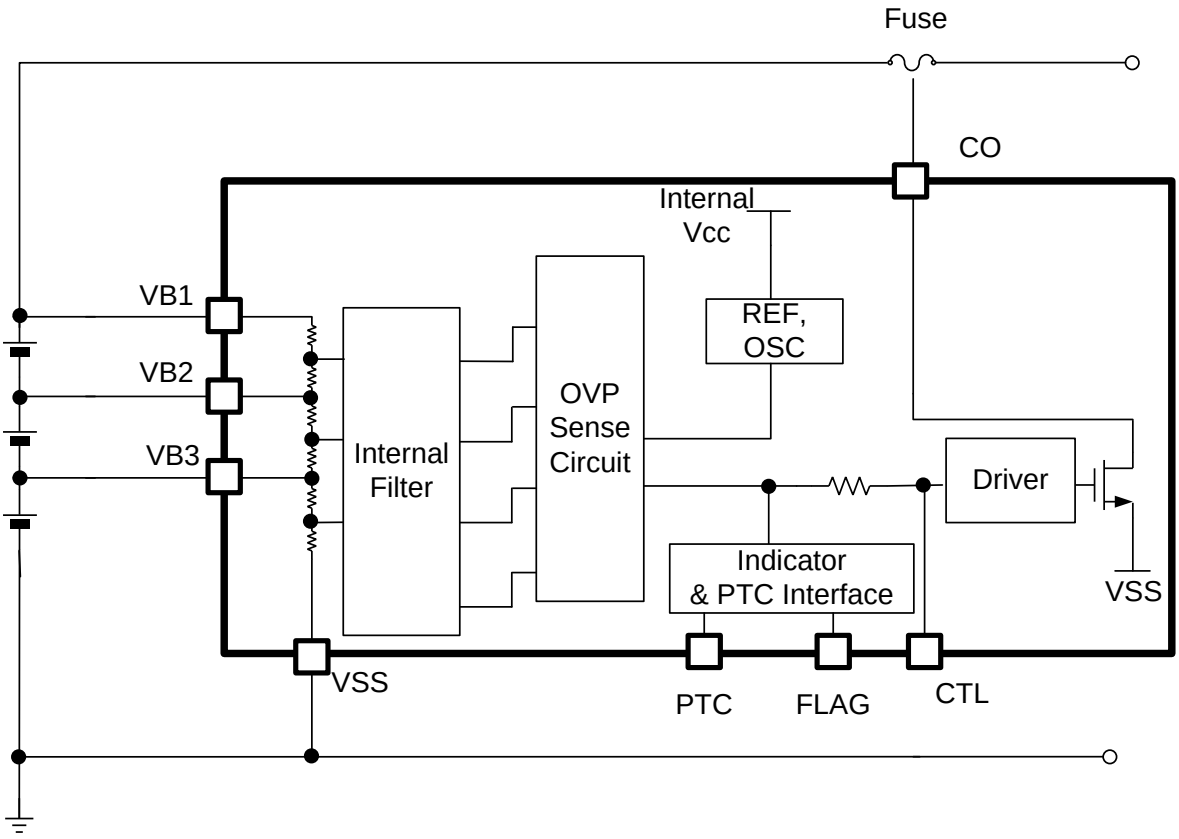


Figure 1: Functional Block Diagram

OPERATION

The MP6420 provides an over-charge protection that integrates a protective, open-drain MOSFET for 2- or 3-series cell Li-ion power systems.

The MP6420 provides a ±25mV, high-accuracy, over-charge threshold to monitor all series' battery pack conditions. With the high-accuracy threshold, the MP6420 provides different fixed thresholds from 4.2V to 4.8V internally. Any cell over-charge turns on the internal protective MOSFET to indicate an error after a fixed, internally set delay time. FLAG is used to indicate an over-voltage protection (OVP) condition, provide a PTC interface, and can control the protective MOSFET externally with CTL.

Over-Voltage Detection

All cells are monitored between VB1 and VB2, VB2 and VB3, and VB3 and VSS. If any of the voltages from these cells rise higher than the over-voltage threshold (V_{OV}), OVP is triggered. The internal MOSFET turns on and remains on until the cell over-voltage status remains longer than the over-charge response delay (T_{OV}). The T_{OV} timer can be reset if the cell voltage drops below the over-threshold voltage and remains longer than the over-charge reset time (T_{OV_RES}). The OVP status is released if all cell voltages fall below the over-voltage release voltage (V_{OV} - V_{OV_H}), and the internal MOSFET turns off again. There is an over-charge release delay (T_{OV_N}) to deglitch noise (see Figure 2).

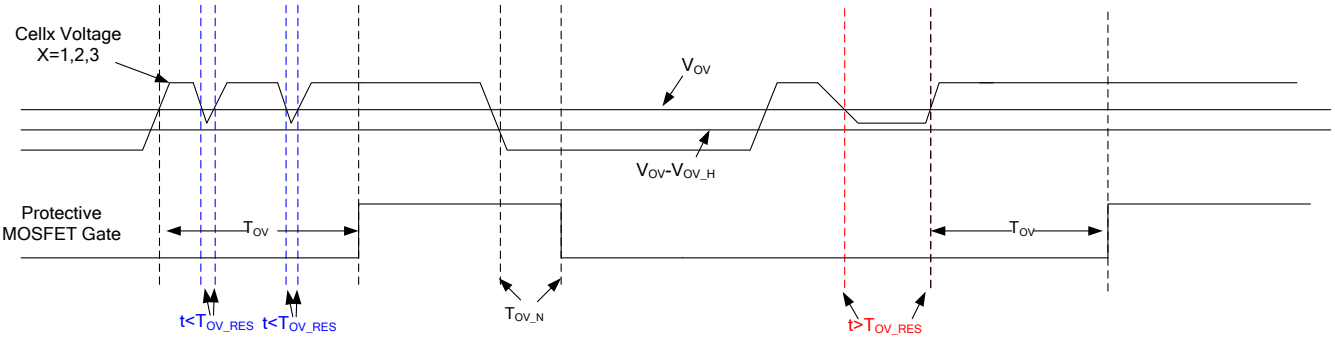


Figure 2: MP6420 Over-Voltage Response

Integrated MOSFET and Filter

Traditionally, secondary battery protection ICs need an external, high-voltage, or large-current MOSFET. Each cell requires an R-C filter to prevent cell voltage noise. The MP6420 provides a fully integrated solution with a protective MOSFET and internal filter. The internal filter has an equivalent 1kΩ/0.1μF external R-C filter performance. This helps lower cost and make the layout easier. The internal protective MOSFET is a 24V/100mΩ device. The filter works with an anti-noise over-voltage comparator, which can monitor the battery voltage.

Over-Discharge Status

The MP6420 saves quiescent current when the voltage on all cells is over-discharged. If the voltage of all the cells is lower than the over-discharge threshold (V_{Dis}), the cell over-voltage monitor block is disabled. The disabled over-charge detection block decreases the quiescent current during an over-discharge status (see Figure 3).

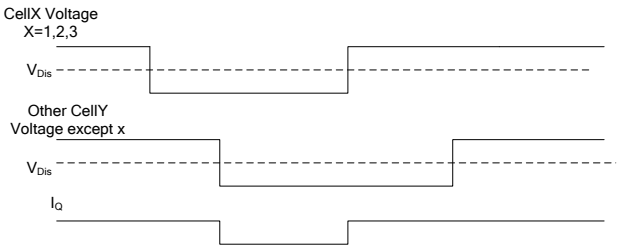


Figure 3: Over-Discharge Status

Shutdown Status

The MP6420 decreases most of the quiescent current during shutdown. When all cell voltages are lower than V_{Dis} and the shutdown voltage (V_{SH}), all over-voltage (OV) monitor blocks are disabled (see Figure 4).

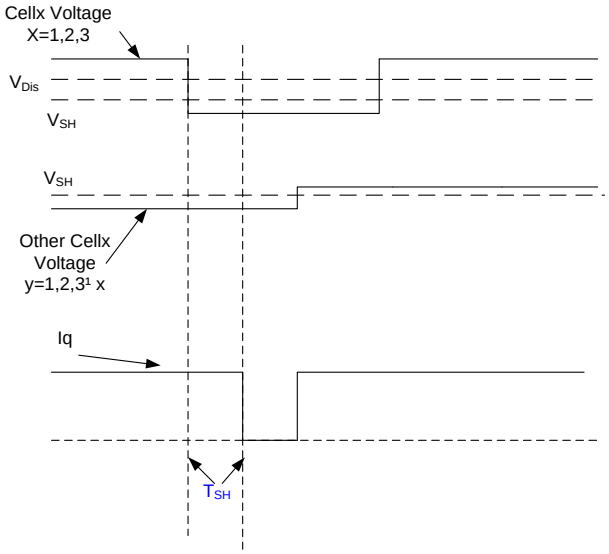


Figure 4: Shutdown Status

FLAG Indicator

FLAG is an indicator pin. Under normal conditions, FLAG is at logic low. When over-charge occurs or over-temperature is detected by PTC, FLAG is pulled up to an internal 5V supply (see Figure 5). FLAG can be floated.

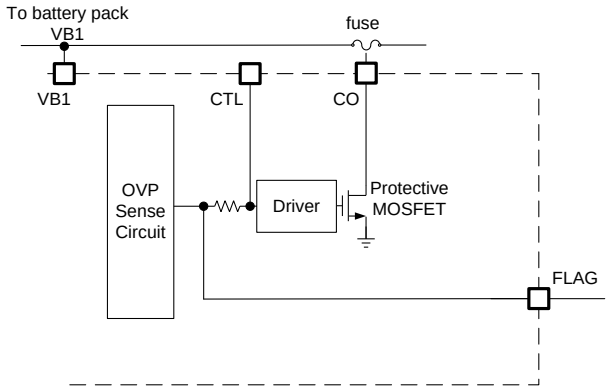


Figure 5: FLAG and CTL Structure

Cell Connection Power Sequence

Since the MP6420 internal VCC is based on VB3, it is recommended to make VB3 the first connection in the power sequence (see Table 1). CTL provides another way to avoid a malfunction during the assembly process. CTL is pulled down to VSS so that the inner protective MOSFET is not active.

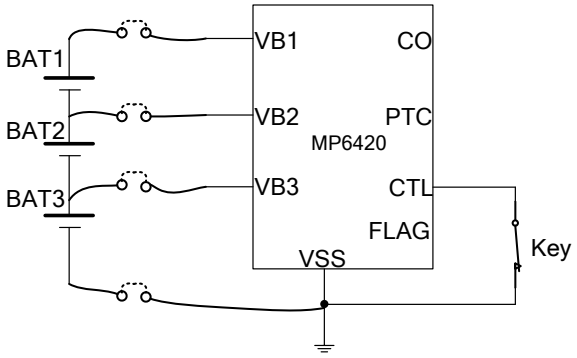


Figure 6: Recommended Safe Operation during Assembly Process

Table 1: Recommended Connection Sequence

Connection Sequence	FLAG Pin Signal				CO Pin Signal			
	Int.	1st	2nd	3rd	Int.	1st	2nd	3rd
→VSS→VB3→VB2→VB1	Low	Low	Low	Low	Low	High	High	High
→VSS→VB3→VB1→VB2	Low	Low	Low	Low	Low	High	High	High

APPLICATION INFORMATION

PTC Interface

PTC can be used to monitor the ambient temperature and turn on the protective MOSFET. PTC cannot be floated. PTC requires a resistor (typically 10kΩ) pulled to VB1 (see Figure 7). When the PTC interface is required, a 10kΩ PTC resistor is recommended. See Table 2 for a list of recommended resistors and manufacturers.

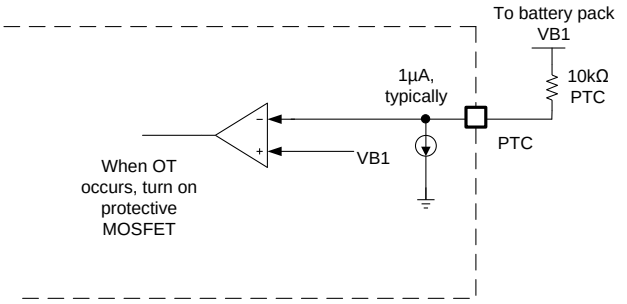


Figure 7: MP6420 PTC Interface

There is an internal sink current source used to pull down the PTC voltage (typically ~1μA). Under normal conditions, the FLAG output is at logic low. With 10kΩ of PTC resistance under room temperature, the PTC voltage is almost equal to VB1. If the sensor PTC resistor monitors high temperatures, the PTC resistance ramps quickly, and the PTC voltage drops. When the PTC voltage is lower than VB1 - 1.2V, the MP6420 triggers PTC protection.

If the PTC function is not needed, a normal 10kΩ resistor is sufficient.

Table 2: Recommended PTC Resistors

Part Number	Description	Vendor
PRF15BB103RB6RC	10kΩ, 130°C	Murata
ECPTH1608103P130ST	10kΩ, 130°C	Joinset

2-/3-Cell Usage

When the MP6420 has more monitor ports than it is using, the unused ports should be shorted. The VB1 - VB3 monitors must be used from the bottom side. For example, if only two cells are used, then VB1 should be shorted to VB2 (see Figure 8).

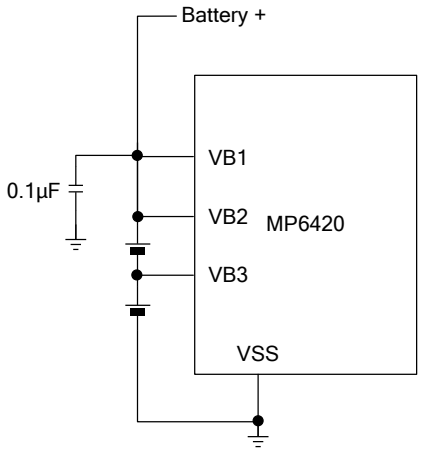


Figure 8: 2-Cell Usage

More than 3-Cell Usage

For applications using a battery with more than three cells, use a MP6420 series circuit (see Figure 9).

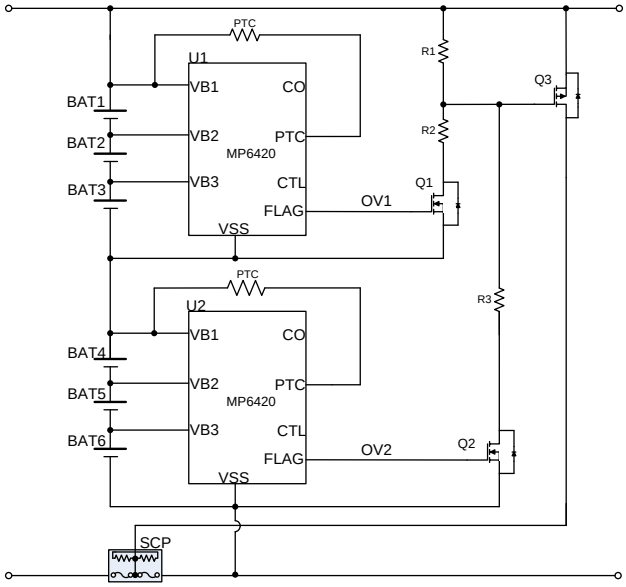


Figure 9: 3-Cell Battery or More Application Circuit

Each FLAG is active high when one-cell OVP is triggered. Q3 then turns on to pull down the self-control protector (SCP). The OR logic circuit consists of extra MOSFETs (Q1, Q2, Q3) and pull-up resistors (R1, R2, R3). Choose MOSFETs and resistors based Equation (1):

$$V_{ds\_max\_Q1}=1.3\times V_{BAT} \quad (1)$$

Where V_{BAT} is the voltage of each cell battery.

When OV1 is low (no OV trigger on U1) and considering a 30% margin, calculate V_{ds} with Equation (2):

$$V_{ds\_max\_Q2}=1.3\times6V_{BAT} \quad (2)$$

The Q2 maximum $V_{ds} = 3V_{BAT}$.

When OV2 is low (no OV trigger on U2) and considering a 30% margin, calculate V_{ds} with Equation (3):

$$V_{ds\_max\_Q3}=1.3\times6V_{BAT} \quad (3)$$

The Q3 maximum $V_{ds} = 6V_{BAT}$.

When both OV1 and OV2 are low (no OV trigger on either cell) and considering a 30% margin, calculate V_{gs} with Equation (4) and Equation (5):

$$V_{gs(th)\_max\_Q3}<3V_{BAT}\times R1/(R1+R2)<V_{gs\_max\_Q3} \quad (4)$$

$$V_{gs(th)\_max\_Q3}<6V_{BAT}\times R1/(R1+R3)<V_{gs\_max\_Q3} \quad (5)$$

Where $V_{gs(th)\_max\_Q3}$ is the maximum gate-to-source threshold voltage, and $V_{gs\_max\_Q3}$ is the maximum gate-to-source voltage of Q3.

Testing Over-Voltage Safely

During the production test, OVP can be tested safely without blowing the fuse. Connect CTL to GND externally. The protective MOSFET gate is pulled to GND. With this configuration, the battery status can be indicated with FLAG (see Figure 10).

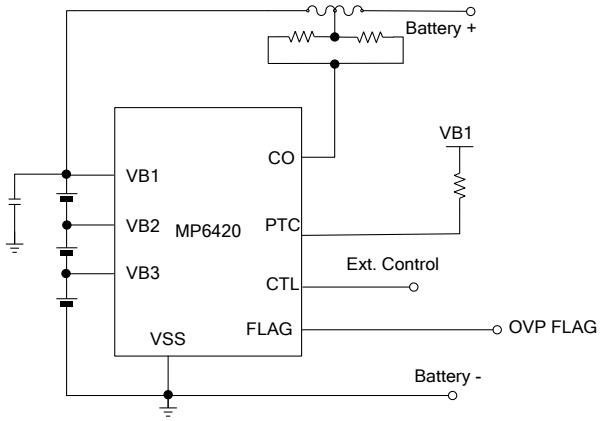


Figure 10: Safe OVP Test

TYPICAL APPLICATION CIRCUIT

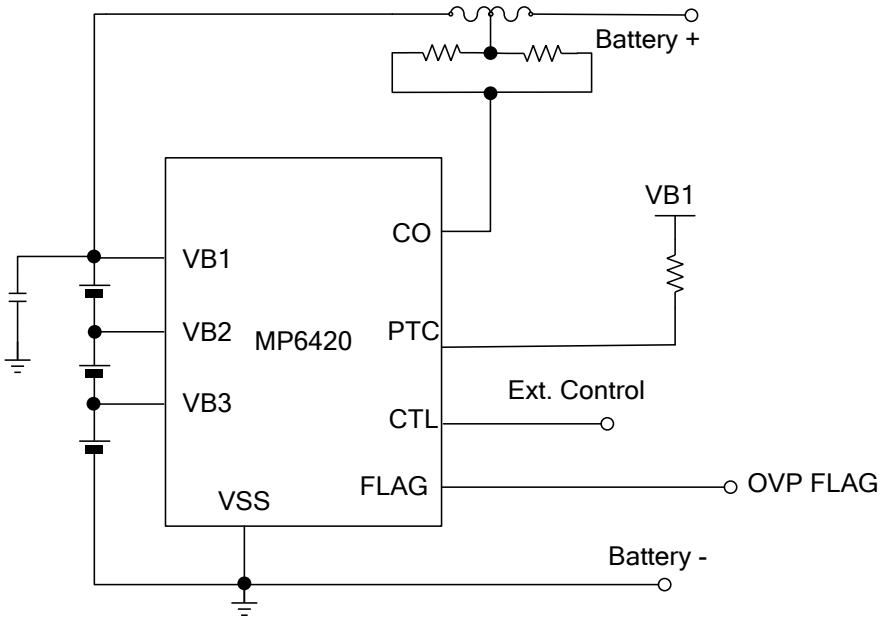
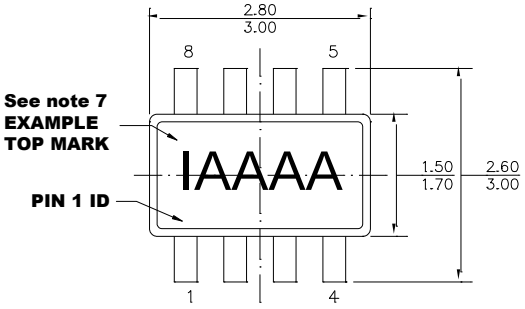


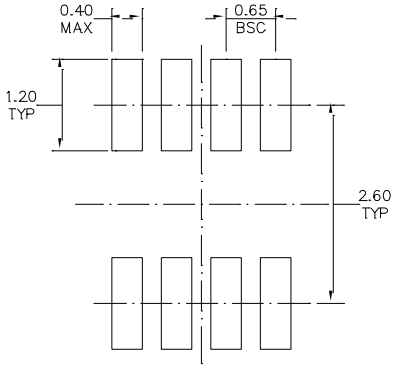
Figure 11: MP6420 Typical Schematic

PACKAGE INFORMATION

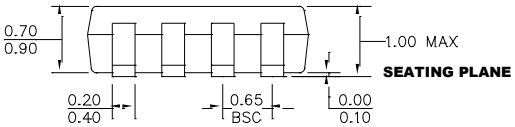
TSOT23-8



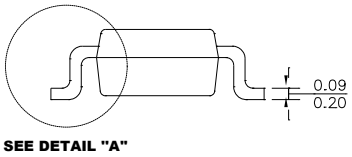
TOP VIEW



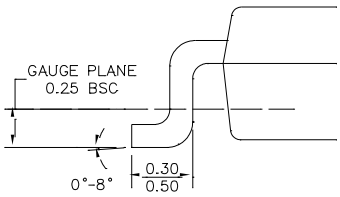
RECOMMENDED LAND PATTERN



FRONT VIEW



SIDE VIEW



DETAIL "A"

NOTE:

1) ALL DIMENSIONS ARE IN MILLIMETERS.
2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR.
3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.10 MILLIMETERS MAX.
5) JEDEC REFERENCE IS MO-193, VARIATION BA.
6) DRAWING IS NOT TO SCALE.
7) PIN 1 IS LOWER LEFT PIN WHEN READING TOP MARK FROM LEFT TO RIGHT, (SEE EXAMPLE TOP MARK)